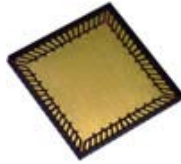


Preplated NiPdAu Cu leadframe for Open cavity (air cavity) QFN semiconductor packages.
Available in three plating thicknesses.

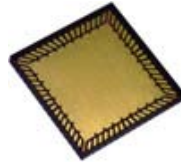
About G5 , G6 and G7 plating thickness:

- G5 : Thick gold plating looks richer. Excellent wire bondability. Good reflow SMT, but occasionally subject to black pad phenomena.
- G7: Medium gold plating appears gold in color. Excellent bondability. Superior reflow SMT solderability.
- G6: Thin gold plating appears silver in color. Excellent bondability. Superior reflow SMT solderability.



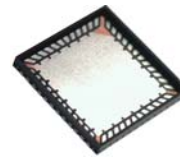
G5 Series
Thick Gold

- Ni 1.27 ~ 4.6 μ m
- Pd 0.15 ~ 0.50 μ m
- Au 0.10 ~ 0.20 μ m



G7 Series
Medium Gold

- Ni 0.50 ~ 2.0 μ m
- Pd 0.02 ~ 0.15 μ m
- Au 0.01 ~ 0.063 μ m



G6 Series
Thin Gold

- Ni 0.50 ~ 2.00 μ m
- Pd 0.02 ~ 0.15 μ m
- Au 0.003 ~ 0.015 μ m

Table 1 of Lead Frame Plating Thickness

Pins	8L DFN	8L QFN	12L	12L	12L	12L	16L	16L	16L	20L	20L	20L	20L
Size	3mm	3mm	3mm	3mm	4mm	4mm	3mm	4mm	5mm	3mm	4mm	5mm	5mm
Pitch	0.65mm	0.65mm	0.5mm	0.65mm	0.65mm	0.8mm	0.5mm	0.65mm	0.8mm	0.4mm	0.5mm	0.65mm	0.8mm
Plating	G7	G5	G6	G7	G7	G7	G6	G5	G7	G7	G5	G7	G7

Preplated PPF: G5 and G6. • Post Plated: G7.

Table 2 of Lead Frame Plating Thickness

Pins	24L	24L	28L	28L	32L	36L	40L	40L	48L	48L	56L	64L	72L	80L
Size	4mm	5mm	4mm	5mm	5mm	5mm	5mm	6mm	6mm	7mm	8mm	9mm	10mm	12mm
Pitch	0.5mm	0.65mm	0.4mm	0.5mm	0.5mm	0.4mm	0.4mm	0.5mm	0.4mm	0.5mm	0.5mm	0.5mm	0.5mm	0.5mm
Plating	G6	G7	G7	G7	G6	G7	G5	G6 G7	G5	G6 G7	G5	G5	G5	G5 G7

Preplated PPF: G5 and G6. • Post Plated: G7.